

3D NAND Flash Memory Market by Type (Single-Level Cell, Multi-Level Cell, and Triple-Level Cell), Application (Cameras, Laptop & PCs, Smartphone & Tablets, and Others), and End Users (Automotive, Consumer Electronics, Enterprise, Healthcare, and Others): Global Opportunity Analysis and Industry Forecast, 2017 - 2025

https://marketpublishers.com/r/3CEC18D52C2EN.html

Date: December 2018

Pages: 255

Price: US\$ 5,370.00 (Single User License)

ID: 3CEC18D52C2EN

Abstracts

3D NAND Flash Memory Market Overview:

The global 3D NAND flash memory market size is expected to be \$ 9,056.2 million in 2017, and is projected to reach \$ 99,769.0 million by 2025, registering a CAGR of 35.3% from 2018 to 2025.

3D NAND flash memory technology has been increasingly utilized in various applications due to increase in demand for data storage. It offers large storage space while operating faster at a rather reduced cost. This technology has considerably evolved as the existing technologies were not able to effectively scale capacity to meet the increase in demand for data storage.

The key market players are trying to develop advanced memory chips for consumer electronics devices with a focus on more in-built storage to reduce the reliance on external memory cards. Micron Technology, for instance, developed a 3D NAND chip in August 2016 for smartphones, which stacks 48 layers of memory cells. The mass production of such chips is yet to start by the company, but this is an advancement in the 3D NAND flash memory market. Moreover, advancements in mobile technology coupled with growth in usage aid the smartphone growth, in terms of penetration. The



global smartphone market is in its mature growth stage due to decline in the overall shipment in developed markets such as the U.S., China, Japan, Canada, and parts of Europe.

The 3D NAND flash memory market is analyzed on the basis of type, application, end user, and geography. On the basis of type, the market is divided into single-level cell (SLC), multi-level cell (MLC), and triple-level cell (TLC). Based on application, the market is categorized into cameras, laptops & PCs, smartphone & tablets, and others. Based on end user, the market is segmented into automotive, consumer electronics, enterprise, healthcare, and others. Geographically, the market is analyzed across North America, Europe, Asia-Pacific, and LAMEA along with their prominent countries.

The key players profiled in the report include Samsung Electronics Co., Ltd., Toshiba Corporation, SK Hynix Semiconductor, Inc., Micron Technology, Inc., Intel Corporation, Apple Inc., Lenovo Group Ltd., Advanced Micro Devices, STMicroelectronics, and SanDisk Corporation.

These key players have adopted strategies such as product portfolio expansion, mergers & acquisitions, agreements, geographical expansion, and collaborations to enhance their market penetration.

Key Benefits for 3d Nand Flash Memory Market:

This study presents the analytical depiction of the global 3D NAND flash memory along with the current trends and future estimations to determine the imminent investment pockets.

The report presents information regarding the key drivers, restraints, and opportunities.

The current market is quantitatively analyzed from 2017 to 2025 to highlight the financial competency of the industry.

Porter's five forces analysis illustrates the potency of the buyers and suppliers in the industry.

3d Nand Flash Memory Market Segmentation:



By Type Single-Level Cell (SLC) Multi-Level Cell (MLC) Triple-Level Cell (TLC) By Application Cameras Laptops & PCs Smartphone & Tablets Others By End User Automotive **Consumer Electronics** Enterprise Healthcare Others By Region North America U.S.



Canada

Mexico		
Europe		
UK		
Germany		
France		
Rest of Europe		
Asia-Pacific		
China		
Japan		
India		
South Korea		
Rest of Asia-Pacific		
LAMEA		
Latin America		
Middle East		
Africa		
Key Market Players Profiled		

Samsung Electronics Co., Ltd.,



Toshiba Corporation,

SK Hynix Semiconductor, Inc.,

Micron Technology, Inc.,

Intel Corporation,

Apple Inc.,

Lenovo Group Ltd.,

Advanced Micro Devices,

STMicroelectronics,

SanDisk Corporation



Contents

CHAPTER: 1: INTRODUCTION

- 1.1. REPORT DESCRIPTION
- 1.2. KEY MARKET SEGMENTS
- 1.3. KEY BENEFITS
- 1.4. RESEARCH METHODOLOGY
 - 1.4.1. PRIMARY RESEARCH
 - 1.4.2. SECONDARY RESEARCH
 - 1.4.3. ANALYST TOOLS AND MODELS

CHAPTER: 2: EXECUTIVE SUMMARY

2.1. CXO PERSPECTIVE

CHAPTER: 3: MARKET LANDSCAPE

- 3.1. MARKET DEFINITION AND SCOPE
- 3.2. KEY FINDINGS
 - 3.2.1. TOP INVESTMENT POCKETS
 - 3.2.2. TOP WINNING STRATEGIES
- 3.3. PORTER'S FIVE FORCES ANALYSIS
 - 3.3.1. BARGAINING POWER OF SUPPLIERS
 - 3.3.2. THREAT OF NEW ENTRANTS
 - 3.3.3. THREAT OF SUBSTITUTES
 - 3.3.4. COMPETITIVE RIVALRY
 - 3.3.5. BARGAINING POWER AMONG BUYERS
- 3.4. MARKET SHARE ANALYSIS/TOP PLAYER POSITIONING
- 3.5. MARKET DYNAMICS
 - 3.5.1. DRIVERS
 - 3.5.2. RESTRAINTS
 - 3.5.3. OPPORTUNITIES

CHAPTER: 4: 3D NAND MARKET MARKET BY TYPE

- 4.1. OVERVIEW
- 4.2. SINGLE LEVEL CELL (SLC)
 - 4.2.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES



- 4.2.2. MARKET SIZE AND FORECAST BY REGION
- 4.2.3. MARKET ANALYSIS BY COUNTRY
- 4.3. MULTI LEVEL CELL MLC
 - 4.3.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 4.3.2. MARKET SIZE AND FORECAST BY REGION
 - 4.3.3. MARKET ANALYSIS BY COUNTRY
- 4.4. TRIPLE LEVEL CELL TLC
 - 4.4.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 4.4.2. MARKET SIZE AND FORECAST BY REGION
 - 4.4.3. MARKET ANALYSIS BY COUNTRY

CHAPTER: 5: 3D NAND MARKET MARKET BY APPLICATION

- 5.1. OVERVIEW
- 5.2. CAMERAS
 - 5.2.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 5.2.2. MARKET SIZE AND FORECAST BY REGION
 - 5.2.3. MARKET ANALYSIS BY COUNTRY
- 5.3. LAPTOPS PCS
 - 5.3.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 5.3.2. MARKET SIZE AND FORECAST BY REGION
 - 5.3.3. MARKET ANALYSIS BY COUNTRY
- **5.4. SMARTPHONE TABLETS**
 - 5.4.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 5.4.2. MARKET SIZE AND FORECAST BY REGION
 - 5.4.3. MARKET ANALYSIS BY COUNTRY
- 5.5. OTHERS
 - 5.5.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 5.5.2. MARKET SIZE AND FORECAST BY REGION
 - 5.5.3. MARKET ANALYSIS BY COUNTRY

CHAPTER: 6: 3D NAND MARKET MARKET BY END USER

- 6.1. OVERVIEW
- 6.2. AUTOMOTIVE
 - 6.2.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 6.2.2. MARKET SIZE AND FORECAST BY REGION
 - 6.2.3. MARKET ANALYSIS BY COUNTRY
- 6.3. CONSUMER ELECTRONICS



- 6.3.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
- 6.3.2. MARKET SIZE AND FORECAST BY REGION
- 6.3.3. MARKET ANALYSIS BY COUNTRY
- 6.4. ENTERPRISE
- 6.4.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
- 6.4.2. MARKET SIZE AND FORECAST BY REGION
- 6.4.3. MARKET ANALYSIS BY COUNTRY
- 6.5. HEALTHCARE
 - 6.5.1. KEY MARKET TRENDS. GROWTH FACTORS AND OPPORTUNITIES
 - 6.5.2. MARKET SIZE AND FORECAST BY REGION
 - 6.5.3. MARKET ANALYSIS BY COUNTRY
- 6.6. OTHERS
 - 6.6.1. KEY MARKET TRENDS, GROWTH FACTORS AND OPPORTUNITIES
 - 6.6.2. MARKET SIZE AND FORECAST BY REGION
 - 6.6.3. MARKET ANALYSIS BY COUNTRY

CHAPTER: 7: 3D NAND MARKET MARKET BY REGION

- 7.1. OVERVIEW
- 7.2. NORTH AMERICA
 - 7.2.1. KEY MARKET TRENDS AND OPPORTUNITIES
 - 7.2.2. MARKET SIZE AND FORECAST BY TYPE
 - 7.2.3. MARKET SIZE AND FORECAST BY APPLICATION
 - 7.2.4. MARKET SIZE AND FORECAST BY END USER
 - 7.2.5. MARKET SIZE AND FORECAST BY COUNTRY
 - 7.2.6. US 3D NAND MARKET MARKET
 - 7.2.6.1. MARKET SIZE AND FORECAST BY TYPE
 - 7.2.6.2. MARKET SIZE AND FORECAST BY APPLICATION
 - 7.2.6.3. MARKET SIZE AND FORECAST BY END USER
 - 7.2.7. CANADA 3D NAND MARKET MARKET
 - 7.2.7.1. MARKET SIZE AND FORECAST BY TYPE
 - 7.2.7.2. MARKET SIZE AND FORECAST BY APPLICATION
 - 7.2.7.3. MARKET SIZE AND FORECAST BY END USER
 - 7.2.8. MEXICO 3D NAND MARKET MARKET
 - 7.2.8.1. MARKET SIZE AND FORECAST BY TYPE
 - 7.2.8.2. MARKET SIZE AND FORECAST BY APPLICATION
 - 7.2.8.3. MARKET SIZE AND FORECAST BY END USER
- 7.3. EUROPE
- 7.3.1. KEY MARKET TRENDS AND OPPORTUNITIES



- 7.3.2. MARKET SIZE AND FORECAST BY TYPE
- 7.3.3. MARKET SIZE AND FORECAST BY APPLICATION
- 7.3.4. MARKET SIZE AND FORECAST BY END USER
- 7.3.5. MARKET SIZE AND FORECAST BY COUNTRY
- 7.3.6. UK 3D NAND MARKET MARKET
- 7.3.6.1. MARKET SIZE AND FORECAST BY TYPE
- 7.3.6.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.3.6.3. MARKET SIZE AND FORECAST BY END USER
- 7.3.7. GERMANY 3D NAND MARKET MARKET
 - 7.3.7.1. MARKET SIZE AND FORECAST BY TYPE
- 7.3.7.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.3.7.3. MARKET SIZE AND FORECAST BY END USER
- 7.3.8. FRANCE 3D NAND MARKET MARKET
 - 7.3.8.1. MARKET SIZE AND FORECAST BY TYPE
- 7.3.8.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.3.8.3. MARKET SIZE AND FORECAST BY END USER
- 7.3.9. REST OF EUROPE 3D NAND MARKET MARKET
 - 7.3.9.1. MARKET SIZE AND FORECAST BY TYPE
- 7.3.9.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.3.9.3. MARKET SIZE AND FORECAST BY END USER

7.4. ASIA PACIFIC

- 7.4.1. KEY MARKET TRENDS AND OPPORTUNITIES
- 7.4.2. MARKET SIZE AND FORECAST BY TYPE
- 7.4.3. MARKET SIZE AND FORECAST BY APPLICATION
- 7.4.4. MARKET SIZE AND FORECAST BY END USER
- 7.4.5. MARKET SIZE AND FORECAST BY COUNTRY
- 7.4.6. CHINA 3D NAND MARKET MARKET
 - 7.4.6.1. MARKET SIZE AND FORECAST BY TYPE
- 7.4.6.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.4.6.3. MARKET SIZE AND FORECAST BY END USER
- 7.4.7. JAPAN 3D NAND MARKET MARKET
 - 7.4.7.1. MARKET SIZE AND FORECAST BY TYPE
- 7.4.7.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.4.7.3. MARKET SIZE AND FORECAST BY END USER
- 7.4.8. INDIA 3D NAND MARKET MARKET
 - 7.4.8.1. MARKET SIZE AND FORECAST BY TYPE
- 7.4.8.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.4.8.3. MARKET SIZE AND FORECAST BY END USER
- 7.4.9. SOUTH KOREA 3D NAND MARKET MARKET



- 7.4.9.1. MARKET SIZE AND FORECAST BY TYPE
- 7.4.9.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.4.9.3. MARKET SIZE AND FORECAST BY END USER
- 7.4.10. REST OF ASIA PACIFIC 3D NAND MARKET MARKET
 - 7.4.10.1. MARKET SIZE AND FORECAST BY TYPE
 - 7.4.10.2. MARKET SIZE AND FORECAST BY APPLICATION
 - 7.4.10.3. MARKET SIZE AND FORECAST BY END USER

7.5. LAMEA

- 7.5.1. KEY MARKET TRENDS AND OPPORTUNITIES
- 7.5.2. MARKET SIZE AND FORECAST BY TYPE
- 7.5.3. MARKET SIZE AND FORECAST BY APPLICATION
- 7.5.4. MARKET SIZE AND FORECAST BY END USER
- 7.5.5. MARKET SIZE AND FORECAST BY COUNTRY
- 7.5.6. LATIN AMERICA 3D NAND MARKET MARKET
- 7.5.6.1. MARKET SIZE AND FORECAST BY TYPE
- 7.5.6.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.5.6.3. MARKET SIZE AND FORECAST BY END USER
- 7.5.7. MIDDLE EAST 3D NAND MARKET MARKET
 - 7.5.7.1. MARKET SIZE AND FORECAST BY TYPE
 - 7.5.7.2. MARKET SIZE AND FORECAST BY APPLICATION
 - 7.5.7.3. MARKET SIZE AND FORECAST BY END USER
- 7.5.8. AFRICA 3D NAND MARKET MARKET
 - 7.5.8.1. MARKET SIZE AND FORECAST BY TYPE
- 7.5.8.2. MARKET SIZE AND FORECAST BY APPLICATION
- 7.5.8.3. MARKET SIZE AND FORECAST BY END USER

CHAPTER: 8: COMPANY PROFILES

- 8.1. SAMSUNG ELECTRONICS CO LTD
 - 8.1.1. COMPANY OVERVIEW
 - 8.1.2. BUSINESS PERFORMANCE
 - 8.1.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.2. TOSHIBA CORPORATION
 - 8.2.1. COMPANY OVERVIEW
 - 8.2.2. BUSINESS PERFORMANCE
 - 8.2.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.3. SK HYNIX SEMICONDUCTOR INC
 - 8.3.1. COMPANY OVERVIEW
- 8.3.2. BUSINESS PERFORMANCE



8.3.3. KEY STRATEGIC MOVES AND DEVELOPMENTS

- 8.4. MICRON TECHNOLOGY INC
 - 8.4.1. COMPANY OVERVIEW
 - 8.4.2. BUSINESS PERFORMANCE
 - 8.4.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.5. INTEL CORPORATION
 - 8.5.1. COMPANY OVERVIEW
 - 8.5.2. BUSINESS PERFORMANCE
 - 8.5.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.6. APPLE INC
 - 8.6.1. COMPANY OVERVIEW
 - 8.6.2. BUSINESS PERFORMANCE
 - 8.6.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.7. LENOVO GROUP LTD
 - 8.7.1. COMPANY OVERVIEW
 - 8.7.2. BUSINESS PERFORMANCE
 - 8.7.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.8. ADVANCED MICRO DEVICES
 - 8.8.1. COMPANY OVERVIEW
 - 8.8.2. BUSINESS PERFORMANCE
 - 8.8.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.9. STMICROELECTRONICS
 - 8.9.1. COMPANY OVERVIEW
 - 8.9.2. BUSINESS PERFORMANCE
 - 8.9.3. KEY STRATEGIC MOVES AND DEVELOPMENTS
- 8.10. SANDISK CORPORATION
 - 8.10.1. COMPANY OVERVIEW
 - 8.10.2. BUSINESS PERFORMANCE
 - 8.10.3. KEY STRATEGIC MOVES AND DEVELOPMENTS



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